

## LF147/LF347 Wide Bandwidth Quad JFET Input Operational Amplifiers

Check for Samples: [LF147](#), [LF347-N](#)

### FEATURES

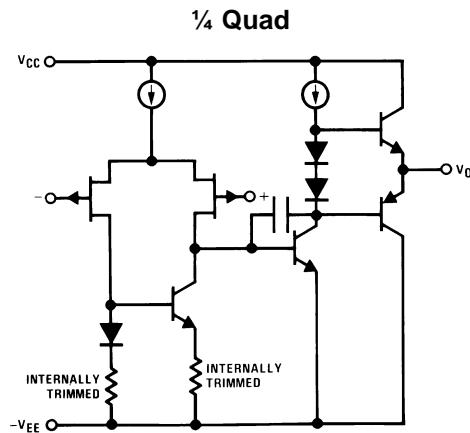
- Internally Trimmed Offset Voltage: 5 mV max
- Low Input Bias Current: 50 pA
- Low Input Noise Current: 0.01 pA/ $\sqrt{\text{Hz}}$
- Wide Gain Bandwidth: 4 MHz
- High Slew Rate: 13 V/ $\mu\text{s}$
- Low Supply Current: 7.2 mA
- High Input Impedance:  $10^{12}\Omega$
- Low Total Harmonic Distortion:  $\leq 0.02\%$
- Low 1/f Noise Corner: 50 Hz
- Fast Settling Time to 0.01%: 2  $\mu\text{s}$

### DESCRIPTION

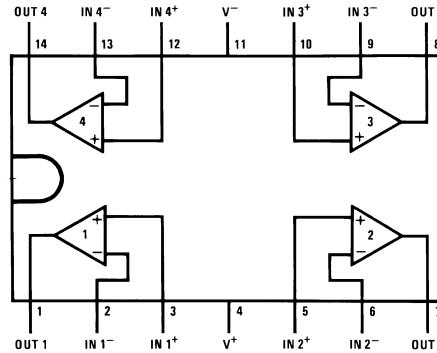
The LF147 is a low cost, high speed quad JFET input operational amplifier with an internally trimmed input offset voltage ( BI-FET II™ technology). The device requires a low supply current and yet maintains a large gain bandwidth product and a fast slew rate. In addition, well matched high voltage JFET input devices provide very low input bias and offset currents. The LF147 is pin compatible with the standard LM148. This feature allows designers to immediately upgrade the overall performance of existing LF148 and LM124 designs.

The LF147 may be used in applications such as high speed integrators, fast D/A converters, sample-and-hold circuits and many other circuits requiring low input offset voltage, low input bias current, high input impedance, high slew rate and wide bandwidth. The device has low noise and offset voltage drift.

### Simplified Schematic



### Connection Diagram



LF147 available as per JM38510/11906.

**Figure 1. 14-Pin PDIP / CDIP / SOIC Top View**

See Package Number **J0014A, D0014A or NFF0014A**



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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 This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

 ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### Absolute Maximum Ratings <sup>(1)(2)</sup>

			LF147	LF347B/LF347
Supply Voltage			±22V	±18V
Differential Input Voltage			±38V	±30V
Input Voltage Range <sup>(3)</sup>			±19V	±15V
Output Short Circuit Duration <sup>(4)</sup>			Continuous	Continuous
Power Dissipation <sup>(5) (6)</sup>			900 mW	1000 mW
T <sub>j</sub> max			150°C	150°C
θ <sub>JA</sub>	CDIP (J) Package			70°C/W
	PDIP (NFF) Package			75°C/W
	SOIC Narrow (D)			100°C/W
	SOIC Wide (D)			85°C/W
Operating Temperature Range			See <sup>(7)</sup>	See <sup>(7)</sup>
Storage Temperature Range			−65°C ≤ T <sub>A</sub> ≤ 150°C	
Lead Temperature (Soldering, 10 sec.)			260°C	260°C
Soldering Information	PDIP / CDIP	Soldering (10 seconds)		260°C
	SOIC Package	Vapor Phase (60 seconds)		215°C
		Infrared (15 seconds)		220°C
ESD Tolerance <sup>(8)</sup>				900V

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (3) Unless otherwise specified the absolute maximum negative input voltage is equal to the negative power supply voltage.
- (4) Any of the amplifier outputs can be shorted to ground indefinitely, however, more than one should not be simultaneously shorted as the maximum junction temperature will be exceeded.
- (5) For operating at elevated temperature, these devices must be derated based on a thermal resistance of θ<sub>JA</sub>.
- (6) Max. Power Dissipation is defined by the package characteristics. Operating the part near the Max. Power Dissipation may cause the part to operate outside ensured limits.
- (7) The LF147 is available in the military temperature range −55°C ≤ T<sub>A</sub> ≤ 125°C, while the LF347B and the LF347 are available in the commercial temperature range 0°C ≤ T<sub>A</sub> ≤ 70°C. Junction temperature can rise to T<sub>j</sub> max = 150°C.
- (8) Human body model, 1.5 kΩ in series with 100 pF.

### DC Electrical Characteristics <sup>(1)(2)</sup>

Symbol	Parameter	Conditions	LF147			LF347B			LF347			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
V <sub>OS</sub>	Input Offset Voltage	R <sub>S</sub> =10 kΩ, T <sub>A</sub> =25°C Over Temperature		1 8		3	5 7		5	10 13		mV mV
ΔV <sub>OS</sub> /ΔT	Average TC of Input Offset Voltage	R <sub>S</sub> =10 kΩ		10		10			10			μV/°C
I <sub>OS</sub>	Input Offset Current	T <sub>j</sub> =25°C, <sup>(2) (3)</sup> Over Temperature		25 25	100		25 4	100		25 4	100 nA	pA nA
I <sub>B</sub>	Input Bias Current	T <sub>j</sub> =25°C, <sup>(2) (3)</sup> Over Temperature		50 50	200		50 8	200		50 8	200 nA	pA nA
R <sub>IN</sub>	Input Resistance	T <sub>j</sub> =25°C		10 <sup>12</sup>		10 <sup>12</sup>			10 <sup>12</sup>			Ω

- (1) Refer to RETS147X for LF147D and LF147J military specifications.
- (2) Unless otherwise specified the specifications apply over the full temperature range and for V<sub>S</sub>=±20V for the LF147 and for V<sub>S</sub>=±15V for the LF347B/LF347. V<sub>OS</sub>, I<sub>B</sub>, and I<sub>OS</sub> are measured at V<sub>CM</sub>=0.
- (3) The input bias currents are junction leakage currents which approximately double for every 10°C increase in the junction temperature, T<sub>j</sub>. Due to limited production test time, the input bias currents measured are correlated to junction temperature. In normal operation the junction temperature rises above the ambient temperature as a result of internal power dissipation, P<sub>D</sub>. T<sub>j</sub>=T<sub>A</sub>+θ<sub>JA</sub> P<sub>D</sub> where θ<sub>JA</sub> is the thermal resistance from junction to ambient. Use of a heat sink is recommended if input bias current is to be kept to a minimum.

**DC Electrical Characteristics <sup>(1)(2)</sup> (continued)**

Symbol	Parameter	Conditions	LF147			LF347B			LF347			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
A <sub>VOL</sub>	Large Signal Voltage Gain Over Temperature	V <sub>S</sub> =±15V, T <sub>A</sub> =25°C V <sub>O</sub> =±10V, R <sub>L</sub> =2 kΩ	50 25	100		50 25	100		25 15	100		V/mV V/mV
V <sub>O</sub>	Output Voltage Swing	V <sub>S</sub> =±15V, R <sub>L</sub> =10 kΩ	±12	±13. 5		±12	±13. 5		±12	±13. 5		V
V <sub>CM</sub>	Input Common-Mode Voltage Range	V <sub>S</sub> =±15V	±11	+15 -12		±11	+15 -12		±11	+15 -12		V V
CMRR	Common-Mode Rejection Ratio	R <sub>S</sub> ≤10 kΩ	80	100		80	100		70	100		dB
PSRR	Supply Voltage Rejection Ratio	See <sup>(4)</sup>	80	100		80	100		70	100		dB
I <sub>S</sub>	Supply Current			7.2	11		7.2	11		7.2	11	mA

(4) Supply voltage rejection ratio is measured for both supply magnitudes increasing or decreasing simultaneously in accordance with common practice from V<sub>S</sub> = ± 5V to ±15V for the LF347 and LF347B and from V<sub>S</sub> = ±20V to ±5V for the LF147.

**AC Electrical Characteristics <sup>(1)(2)</sup>**

Symbol	Parameter	Conditions	LF147			LF347B			LF347			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	Amplifier to Amplifier Coupling	T <sub>A</sub> =25°C, f=1 Hz–20 kHz (Input Referred)		-120			-120			-120		dB
SR	Slew Rate	V <sub>S</sub> =±15V, T <sub>A</sub> =25°C	8	13		8	13		8	13		V/μs
GBW	Gain-Bandwidth Product	V <sub>S</sub> =±15V, T <sub>A</sub> =25°C	2.2	4		2.2	4		2.2	4		MHz
e <sub>n</sub>	Equivalent Input Noise Voltage	T <sub>A</sub> =25°C, R <sub>S</sub> =100Ω, f=1000 Hz		20			20			20		nV / √Hz
i <sub>n</sub>	Equivalent Input Noise Current	T <sub>j</sub> =25°C, f=1000 Hz		0.01			0.01			0.01		pA / √Hz
THD	Total Harmonic Distortion	A <sub>V</sub> =+10, R <sub>L</sub> =10k, V <sub>O</sub> =20 Vp-p, BW=20 Hz–20 kHz		<0.0 2			<0.0 2			<0.0 2		%

(1) Unless otherwise specified the specifications apply over the full temperature range and for V<sub>S</sub>=±20V for the LF147 and for V<sub>S</sub>=±15V for the LF347B/LF347. V<sub>OS</sub>, I<sub>B</sub>, and I<sub>S</sub> are measured at V<sub>CM</sub>=0.  
(2) Refer to RETS147X for LF147D and LF147J military specifications.

### Typical Performance Characteristics

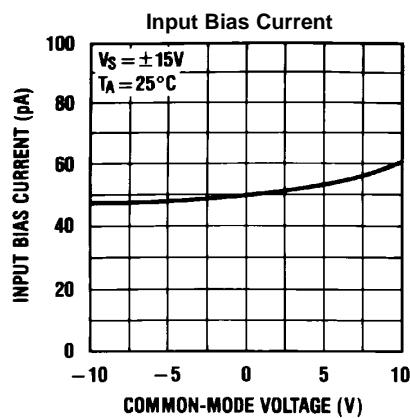


Figure 2.

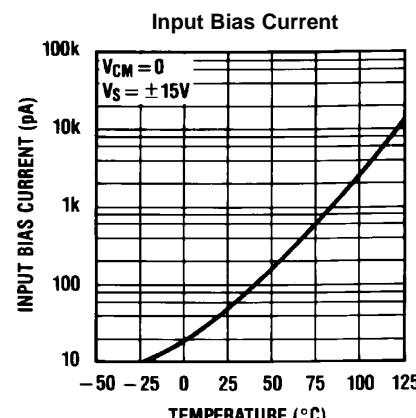


Figure 3.

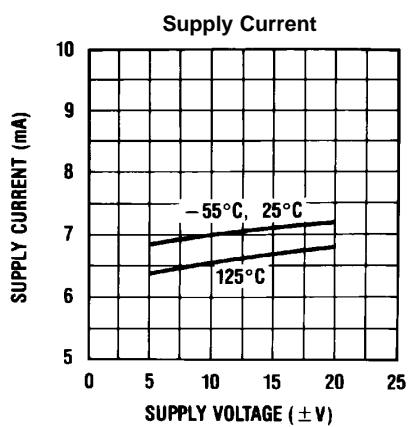


Figure 4.

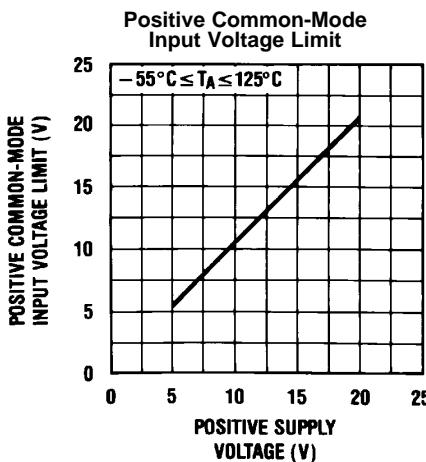


Figure 5.

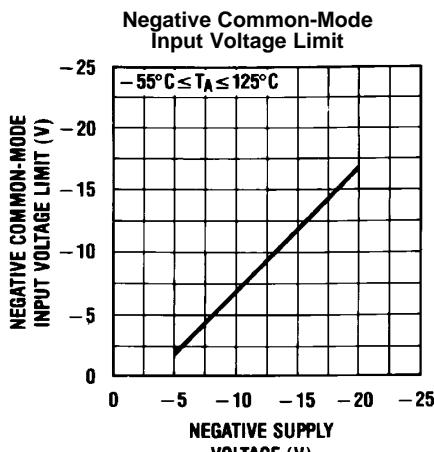


Figure 6.

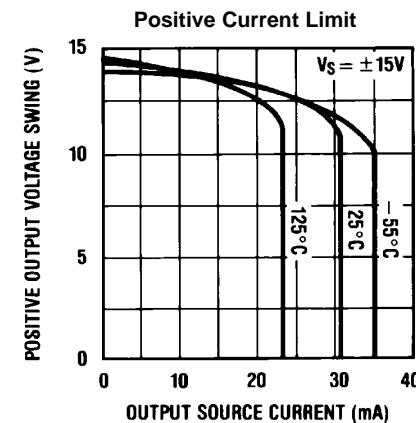


Figure 7.

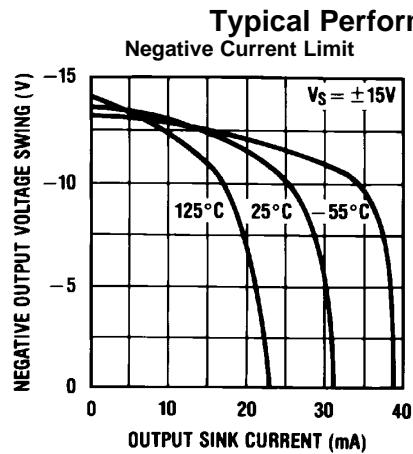


Figure 8.

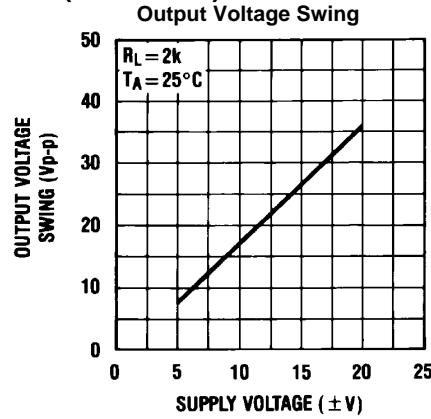


Figure 9.

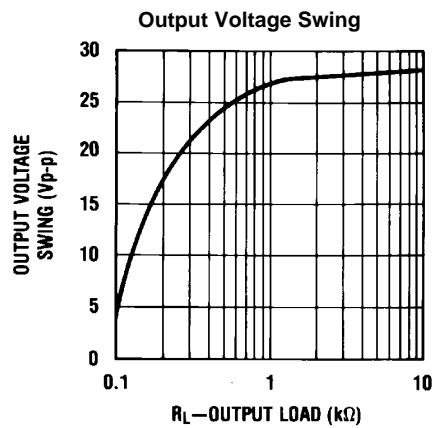


Figure 10.

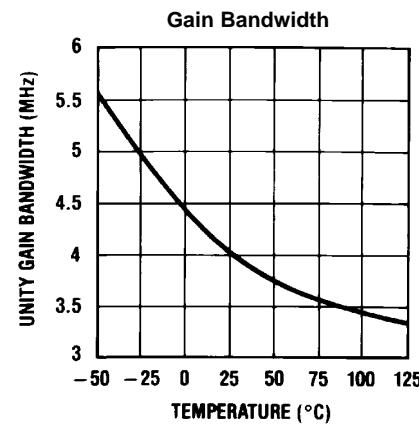


Figure 11.

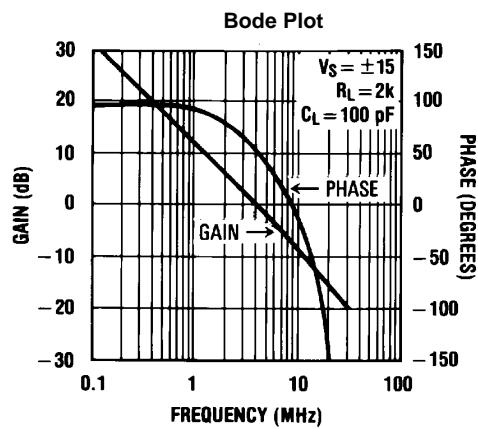


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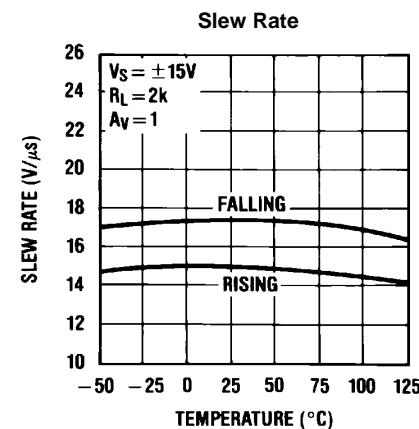
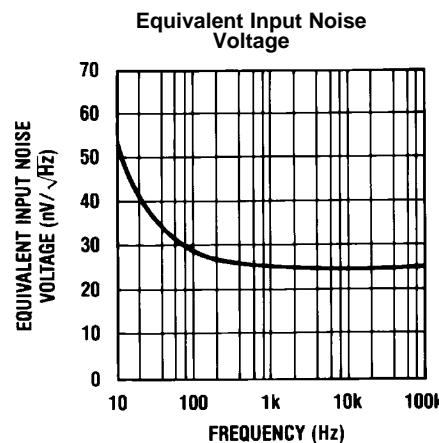
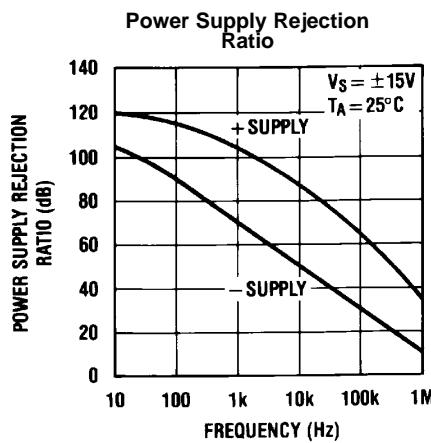
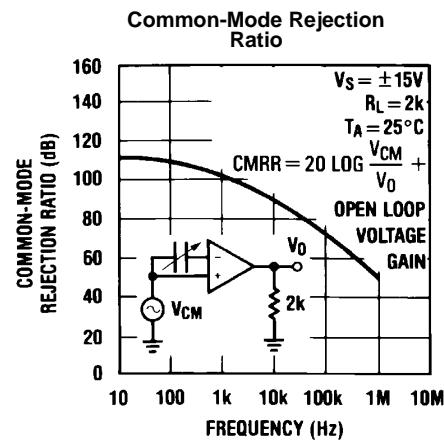
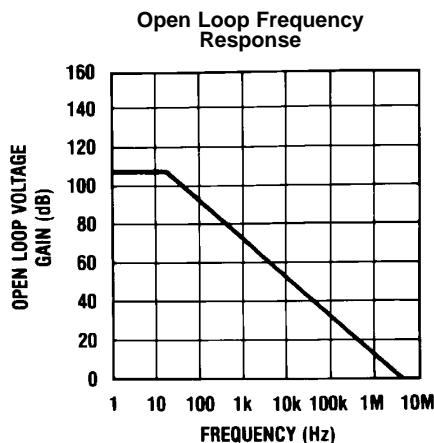
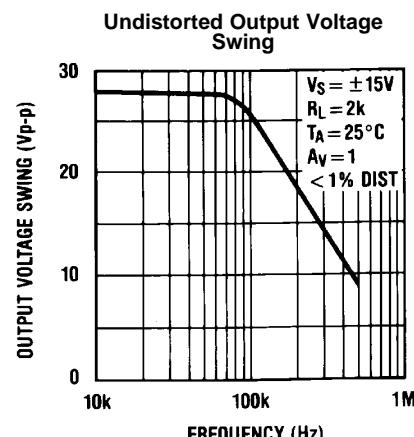
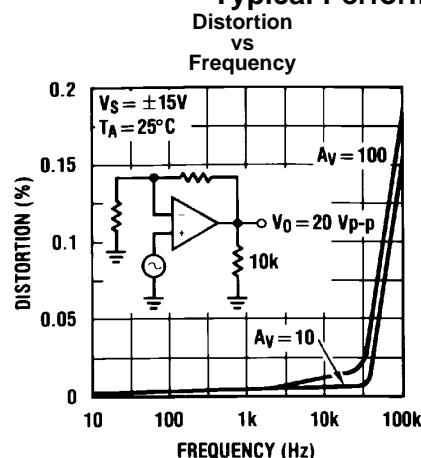


Figure 13.

### Typical Performance Characteristics (continued)



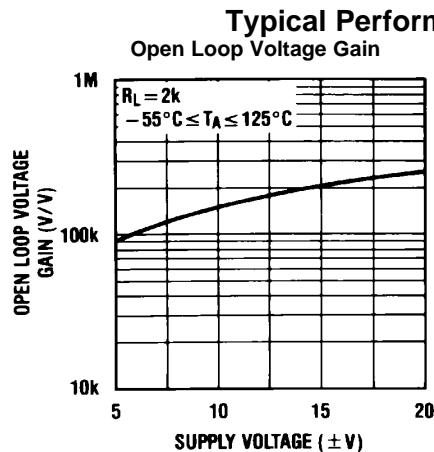


Figure 20.

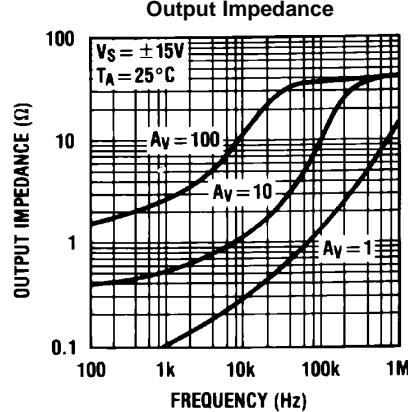


Figure 21.

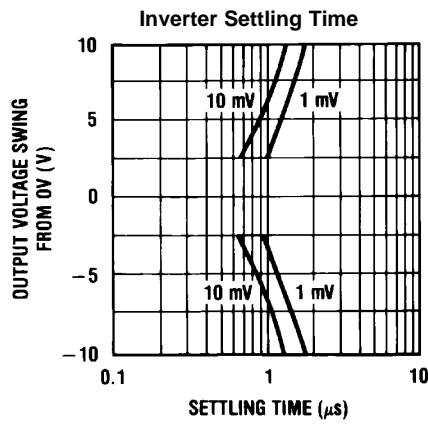
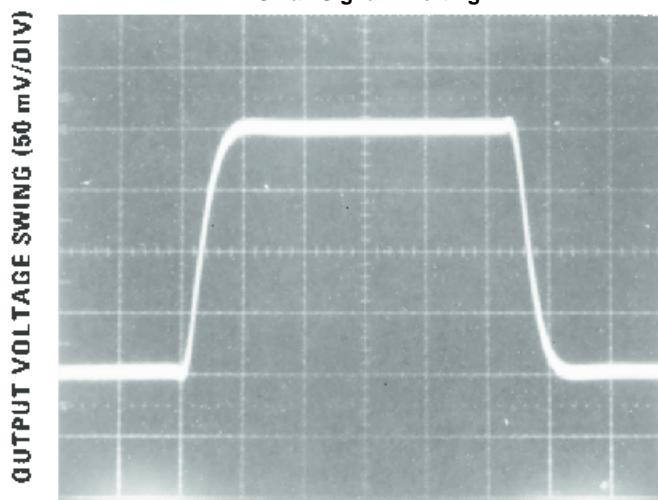


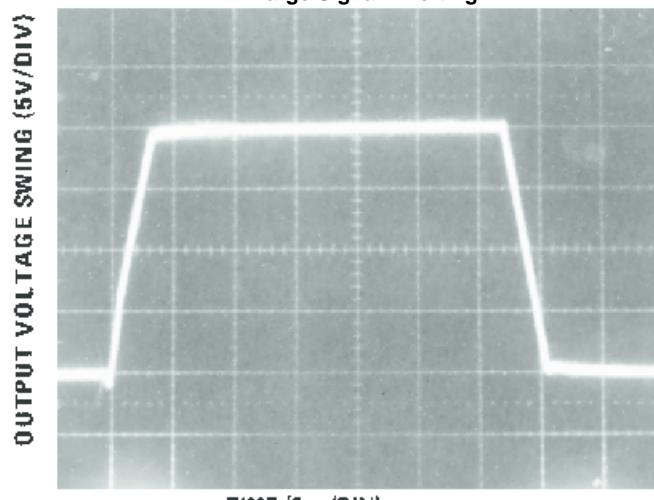
Figure 22.

**Pulse Response** $R_L=2\text{ k}\Omega$ ,  $C_L=10\text{ pF}$ 

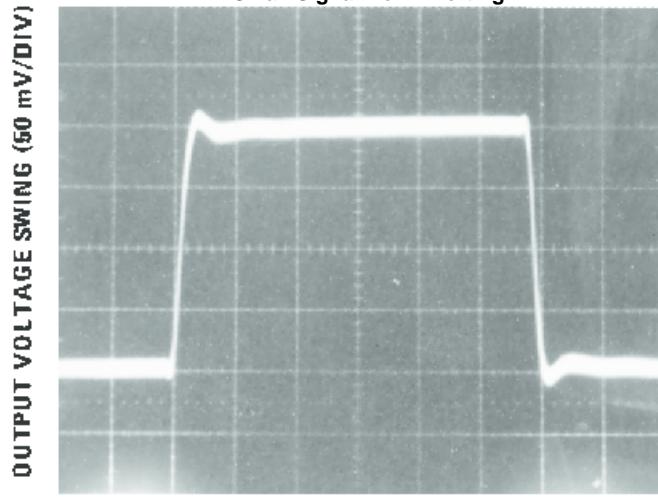
Small Signal Inverting



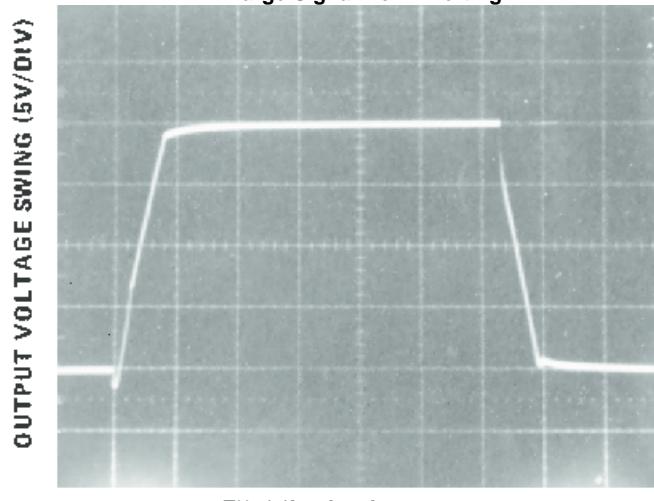
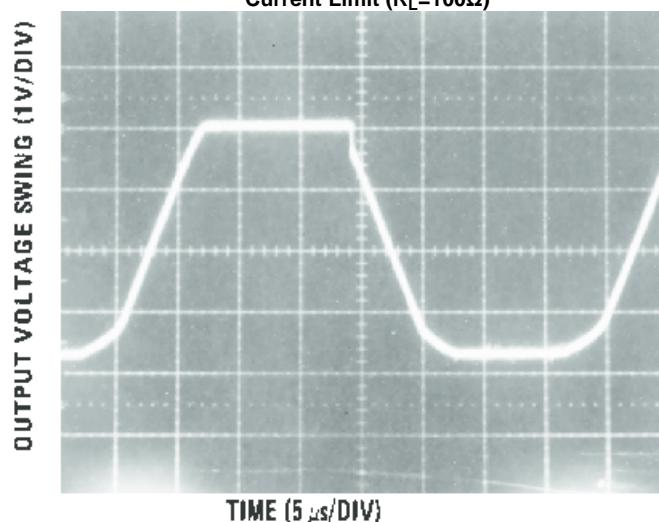
Large Signal Inverting



Small Signal Non-Inverting



Large Signal Non-Inverting

Current Limit ( $R_L=100\Omega$ )

## APPLICATION HINTS

The LF147 is an op amp with an internally trimmed input offset voltage and JFET input devices (BI-FET II). These JFETs have large reverse breakdown voltages from gate to source and drain eliminating the need for clamps across the inputs. Therefore, large differential input voltages can easily be accommodated without a large increase in input current. The maximum differential input voltage is independent of the supply voltages. However, neither of the input voltages should be allowed to exceed the negative supply as this will cause large currents to flow which can result in a destroyed unit.

Exceeding the negative common-mode limit on either input will force the output to a high state, potentially causing a reversal of phase to the output. Exceeding the negative common-mode limit on both inputs will force the amplifier output to a high state. In neither case does a latch occur since raising the input back within the common-mode range again puts the input stage and thus the amplifier in a normal operating mode.

Exceeding the positive common-mode limit on a single input will not change the phase of the output; however, if both inputs exceed the limit, the output of the amplifier will be forced to a high state.

The amplifiers will operate with a common-mode input voltage equal to the positive supply; however, the gain bandwidth and slew rate may be decreased in this condition. When the negative common-mode voltage swings to within 3V of the negative supply, an increase in input offset voltage may occur.

Each amplifier is individually biased by a zener reference which allows normal circuit operation on  $\pm 4.5V$  power supplies. Supply voltages less than these may result in lower gain bandwidth and slew rate.

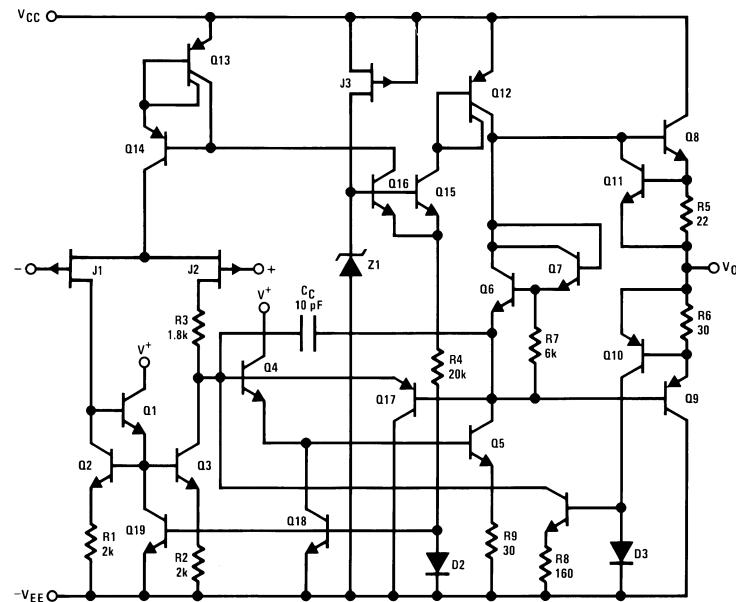
The LF147 will drive a  $2\text{ k}\Omega$  load resistance to  $\pm 10\text{V}$  over the full temperature range. If the amplifier is forced to drive heavier load currents, however, an increase in input offset voltage may occur on the negative voltage swing and finally reach an active current limit on both positive and negative swings.

Precautions should be taken to ensure that the power supply for the integrated circuit never becomes reversed in polarity or that the unit is not inadvertently installed backwards in a socket as an unlimited current surge through the resulting forward diode within the IC could cause fusing of the internal conductors and result in a destroyed unit.

As with most amplifiers, care should be taken with lead dress, component placement and supply decoupling in order to ensure stability. For example, resistors from the output to an input should be placed with the body close to the input to minimize "pick-up" and maximize the frequency of the feedback pole by minimizing the capacitance from the input to ground.

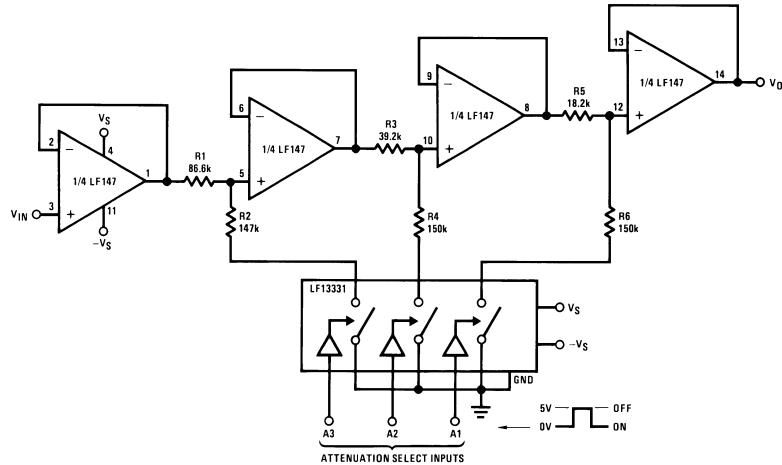
A feedback pole is created when the feedback around any amplifier is resistive. The parallel resistance and capacitance from the input of the device (usually the inverting input) to AC ground set the frequency of the pole. In many instances the frequency of this pole is much greater than the expected 3 dB frequency of the closed loop gain and consequently there is negligible effect on stability margin. However, if the feedback pole is less than approximately 6 times the expected 3 dB frequency a lead capacitor should be placed from the output to the input of the op amp. The value of the added capacitor should be such that the RC time constant of this capacitor and the resistance it parallels is greater than or equal to the original feedback pole time constant.

## Detailed Schematic



## Typical Applications

**Figure 23. Digitally Selectable Precision Attenuator**

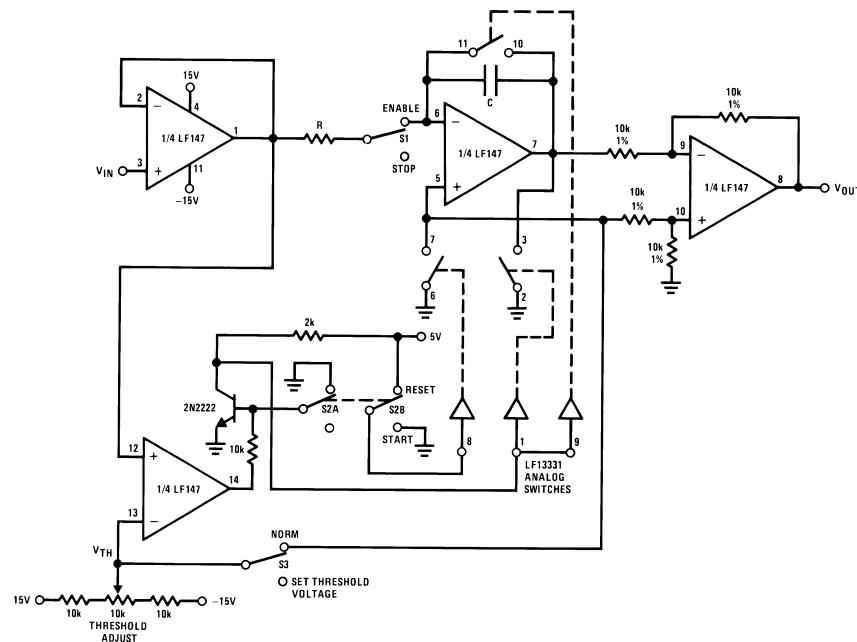


All resistors 1% tolerance

- Accuracy of better than 0.4% with standard 1% value resistors  
No offset adjustment necessary
- Expandable to any number of stages
- Very high input impedance

A1	A2	A3	V <sub>O</sub> Attenuation
0	0	0	0
0	0	1	-1 dB
0	1	0	-2 dB
0	1	1	-3 dB
1	0	0	-4 dB
1	0	1	-5 dB
1	1	0	-6 dB
1	1	1	-7 dB

**Figure 24. Long Time Integrator with Reset, Hold and Starting Threshold Adjustment**

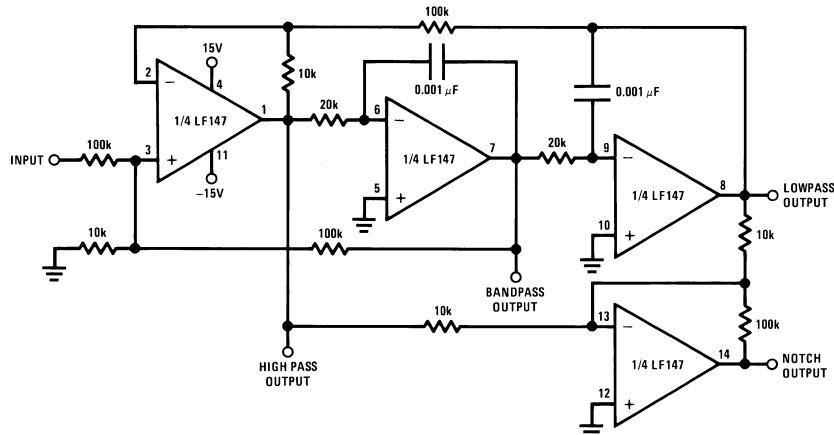


- $V_{OUT}$  starts from zero and is equal to the integral of the input voltage with respect to the threshold voltage:

$$V_{OUT} = \frac{1}{RC} \int_0^t (V_{IN} - V_{TH}) dt$$

- Output starts when  $V_{IN} \geq V_{TH}$
- Switch S1 permits stopping and holding any output value
- Switch S2 resets system to zero

**Figure 25. Universal State Variable Filter**



For circuit shown:

For circuit shown:

### Q=3.4

- Passband gain:
  - Highpass—0.1
  - Bandpass—1
  - Lowpass—1
  - Notch—10
- $f_0 \times Q \leq 200$  kHz
- 10V peak sinusoidal output swing without slew limiting to 200 kHz
- See LM148 data sheet for design equations

## REVISION HISTORY

<b>Changes from Revision C (March 2013) to Revision D</b>	<b>Page</b>
• Changed layout of National Data Sheet to TI format .....	<a href="#">12</a>

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LF147-MD8	Active	Production	DIESALE (Y)   0	100   JEDEC TRAY (5+1)	Yes	Call TI	Level-1-NA-UNLIM	-55 to 125	
LF147J	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	Level-1-NA-UNLIM	-55 to 125	LF147J
LF347BN/NOPB	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	0 to 70	LF347BN
LF347BN/NOPB.B	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	0 to 70	LF347BN
LF347M/NOPB	Active	Production	SOIC (D)   14	55   TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LF347M
LF347M/NOPB.B	Active	Production	SOIC (D)   14	55   TUBE	Yes	SN	Level-1-260C-UNLIM	0 to 70	LF347M
LF347MX/NOPB	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LF347M
LF347MX/NOPB.B	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	0 to 70	LF347M
LF347N/NOPB	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	0 to 70	LF347N
LF347N/NOPB.B	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	0 to 70	LF347N
LF347N/NOPBG4	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	0 to 70	LF347N
LF347N/NOPBG4.B	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	Level-1-NA-UNLIM	0 to 70	LF347N

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

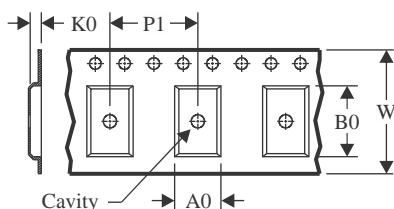
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Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

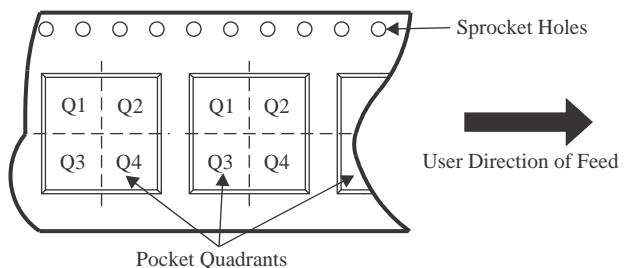
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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LF347MX/NOPB	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LF347MX/NOPB	SOIC	D	14	2500	367.0	367.0	35.0

**TUBE**


\*All dimensions are nominal

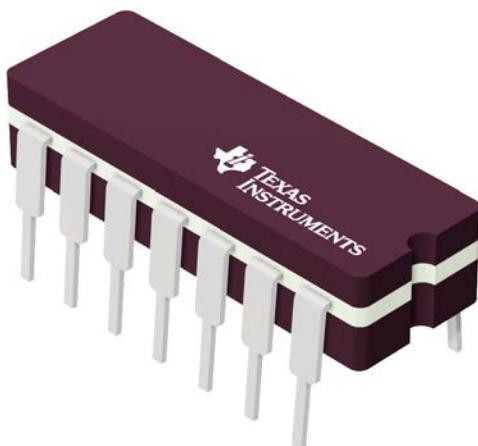
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
LF147J	J	CDIP	14	25	502	14	11938	4.32
LF347BN/NOPB	N	PDIP	14	25	502	14	11938	4.32
LF347BN/NOPB.B	N	PDIP	14	25	502	14	11938	4.32
LF347M/NOPB	D	SOIC	14	55	495	8	4064	3.05
LF347M/NOPB.B	D	SOIC	14	55	495	8	4064	3.05
LF347N/NOPB	N	PDIP	14	25	502	14	11938	4.32
LF347N/NOPB.B	N	PDIP	14	25	502	14	11938	4.32
LF347N/NOPBG4	N	PDIP	14	25	502	14	11938	4.32
LF347N/NOPBG4.B	N	PDIP	14	25	502	14	11938	4.32

# GENERIC PACKAGE VIEW

**J 14**

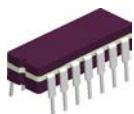
**CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

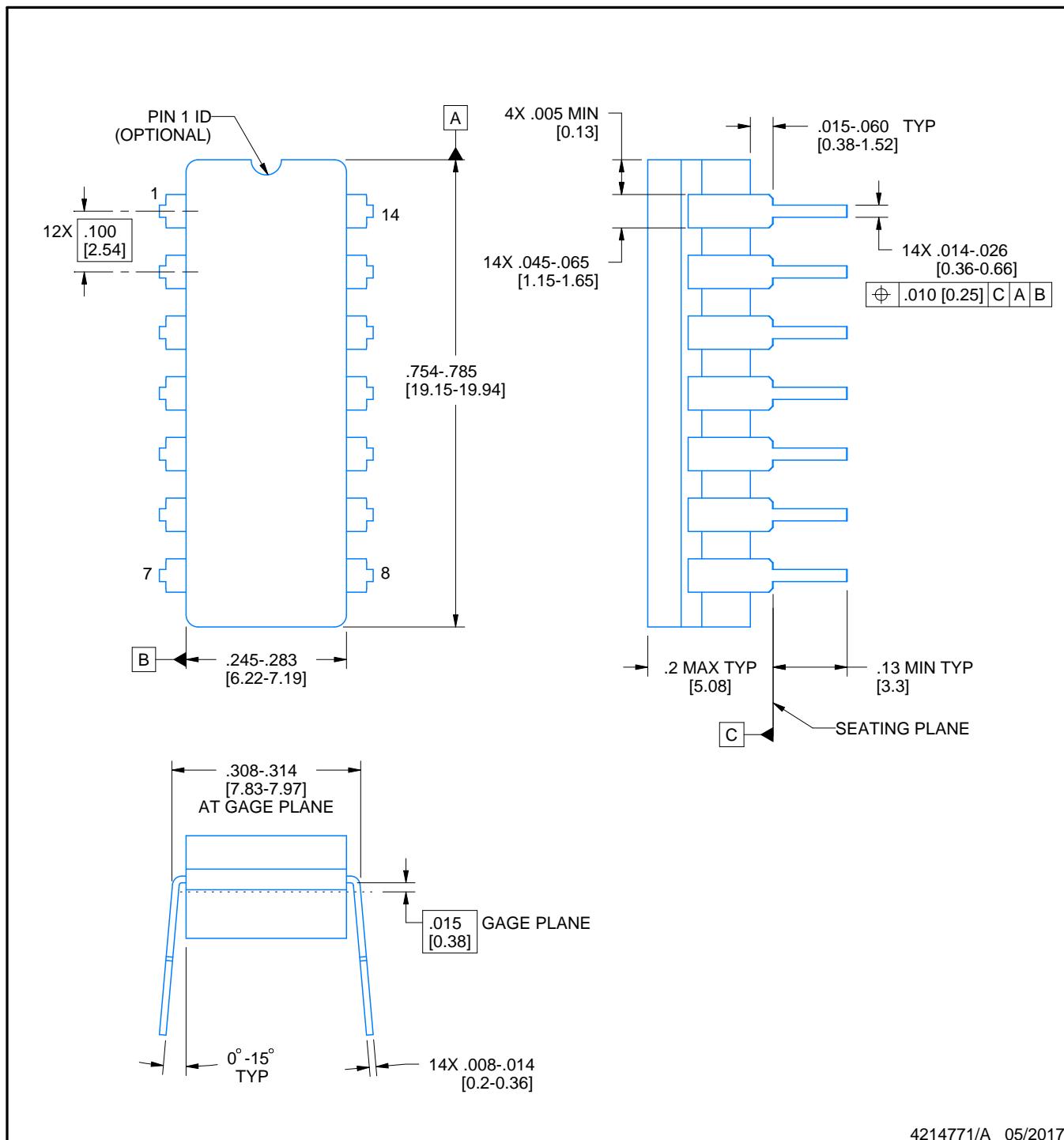


# PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

## NOTES:

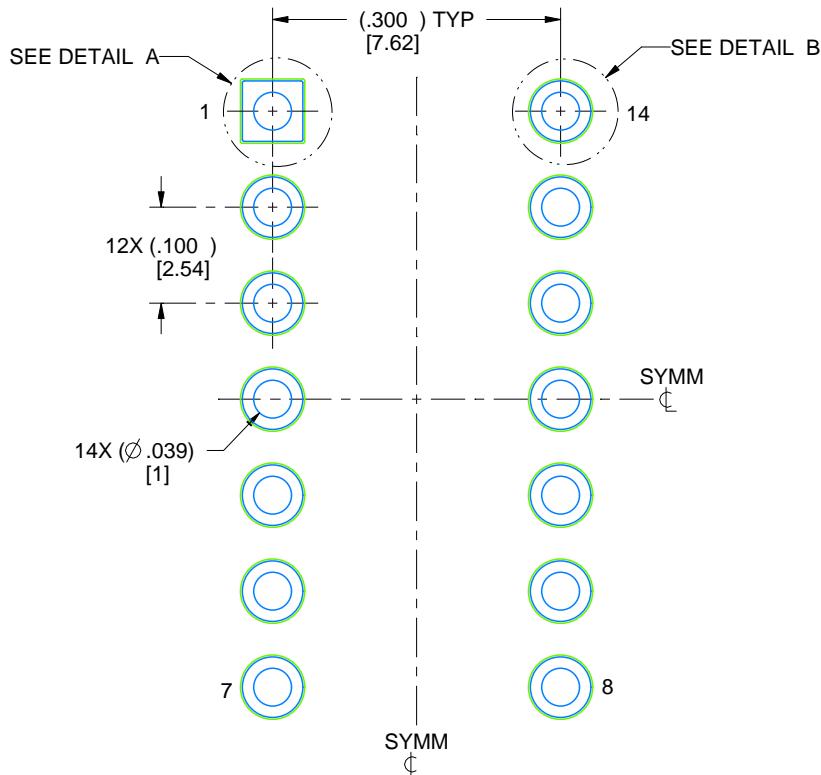
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

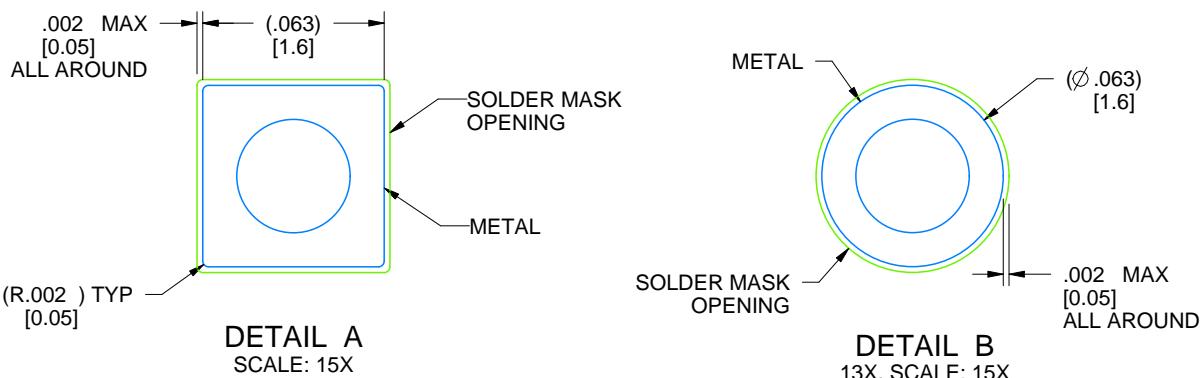
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X

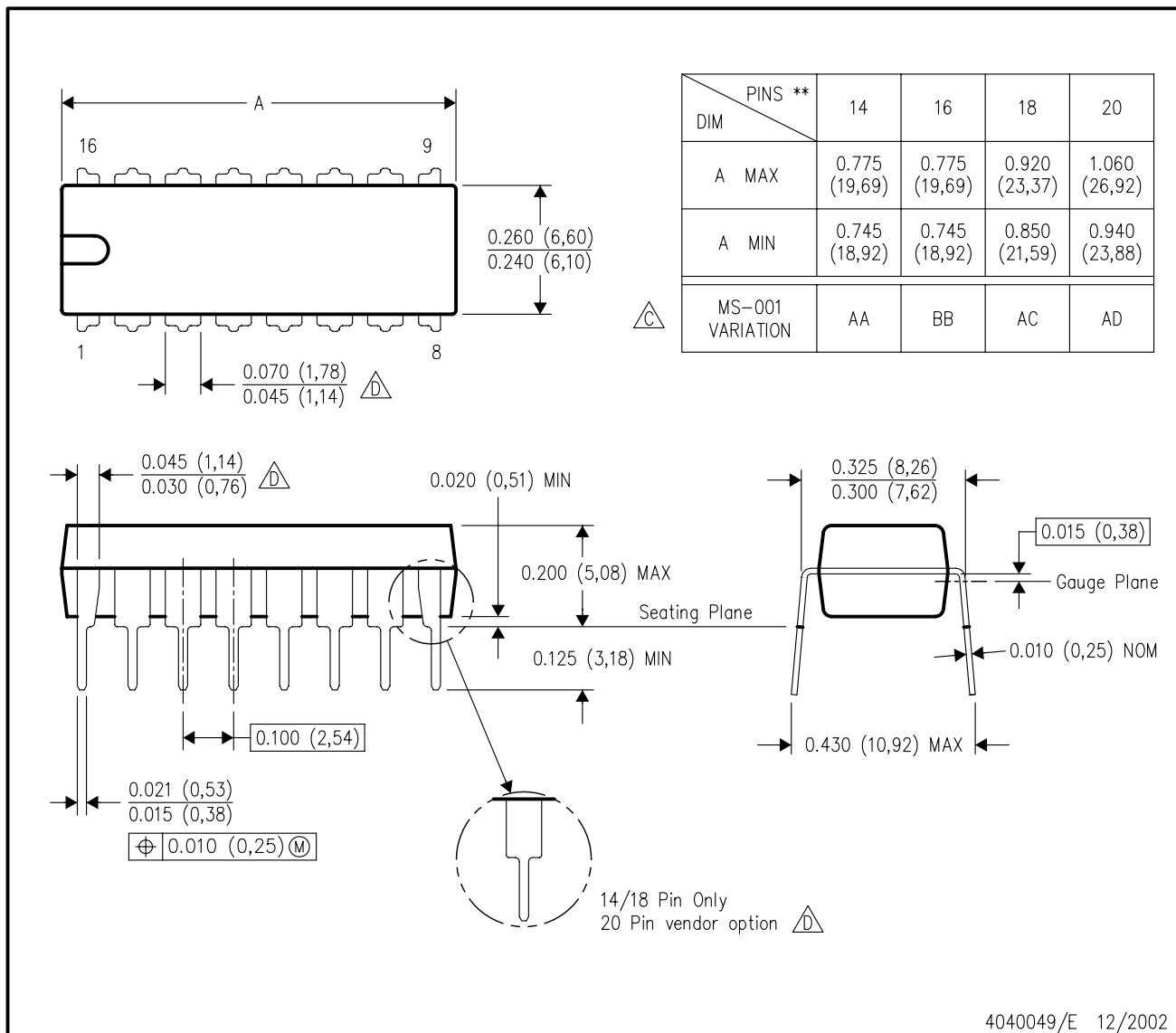


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## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE

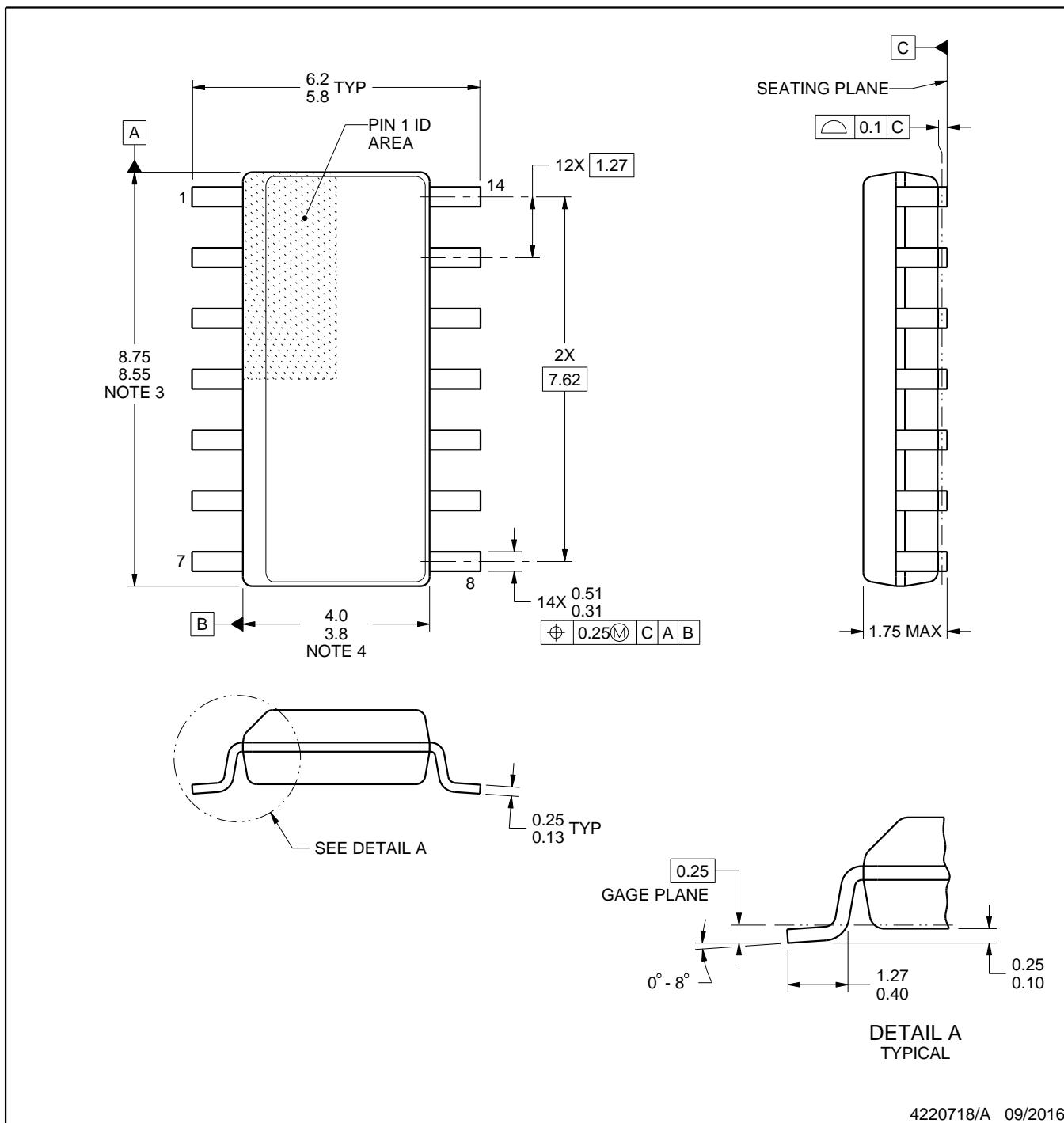


# PACKAGE OUTLINE

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

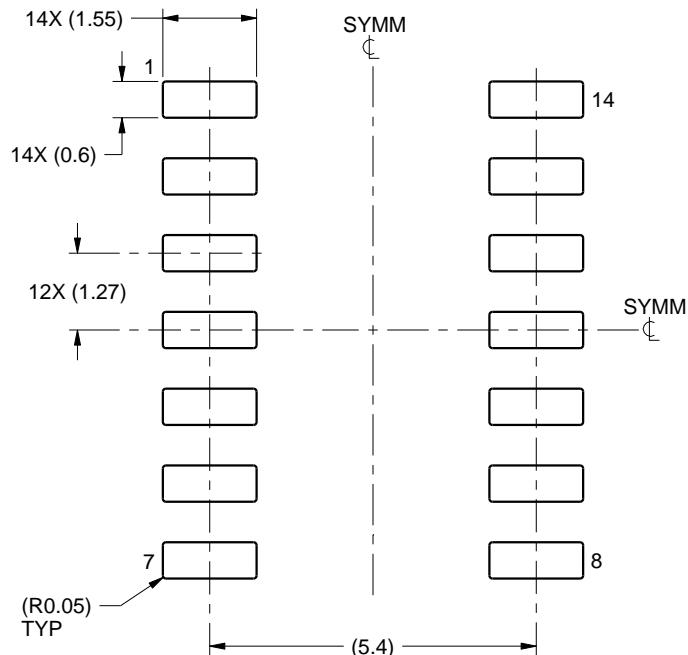
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

# EXAMPLE BOARD LAYOUT

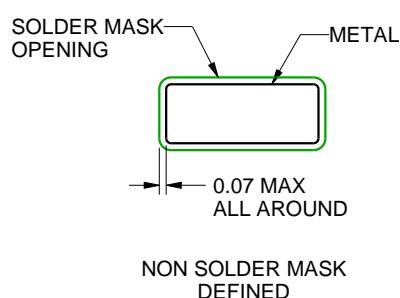
D0014A

SOIC - 1.75 mm max height

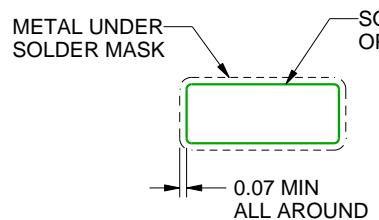
SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



NON SOLDER MASK  
DEFINED



SOLDER MASK  
DEFINED

SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

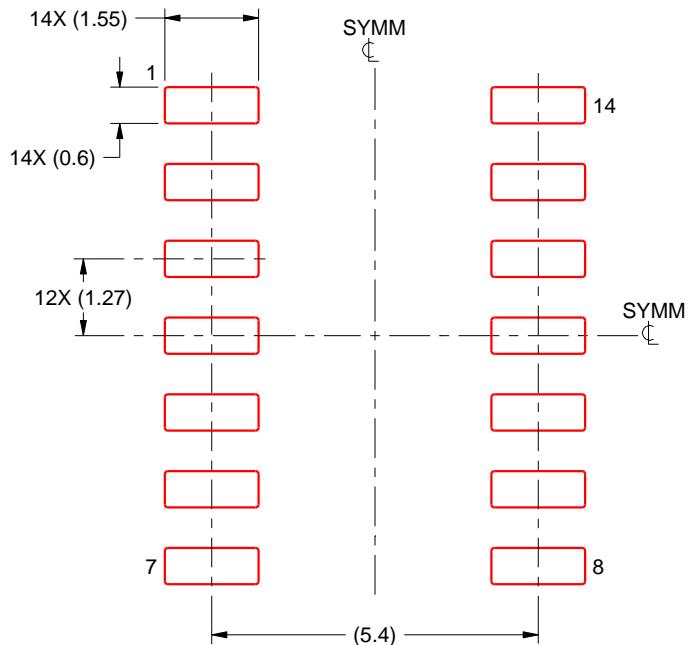
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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